L	Hits	Search Text	DB	Time stamp
Number				
	0	(printed adj wiring adj board) and (carrier adj substrate) and (vapor with copper) and (electrodeposited with copper)	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:45
-	109	(printed adj wiring adj board) and (carrier adj substrate)	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:45
-	71	((printed adj wiring adj board) and (carrier adj substrate)) and copper	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:45
-	56	(((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat\$4	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:46
-	24	<pre>((((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat\$4) and oxide</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:46
-	20	<pre>(((((printed adj wiring adj board) and (carrier adj substrate)) and copper) and separat\$4) and oxide) and (separat\$4 with substrate)</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:53
-	1309	((wiring adj board) and (separat\$4 with (substrate or carrier)))	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:53
-	203	((wiring adj board) and (separat\$4 with (substrate or carrier))).ab.	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 06:54
-	32	(((wiring adj board) and (separat\$4 with (substrate or carrier))).ab.) and copper	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 07:04
_	9	"3984598" "3998601" "4293617" "4357395" "4394419" "5863410").PN.	USPAT	2003/07/28 06:56
. -		<pre>(substrate or carrier))).ab.) and copper) and (vapor or cvd)</pre>	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/07/28 07:10
-	3	((copper adj foil) and (vapor or cvd or deposition) and (separat\$4 with (substrate or carrier)).ab.	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 07:12
_	232	((copper adj foil) and (vapor or cvd or deposition)).ab.	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 07:13
-	10	(((copper adj foil) and (vapor or cvd or deposition)).ab.) and (electroplat\$4 with copper)	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 07:18
-	586	((vapor or cvd) with copper) with ((electroplat\$4 or electrodepos\$5) with copper)	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28
-	0	<pre>(((vapor or cvd) with copper) with ((electroplat\$4 or electrodepos\$5) with copper).ab.) and coppper and foil</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28
-	61	((vapor or cvd) with copper) with ((electroplat\$4 or electrodepos\$5) with copper).ab.	USPAT; EPO; JPO; DERWENT; IBM TDB	2003/07/28 07:20

	•		
 63	257/251.ccls.	USPAT;	2003/07/28
		EPO; JPO;	07:41
		DERWENT;	
		IBM TDB	